1.6x0.2mm RIGHT ANGLE SMD CHIP LED LAMP

PRELIMINARY SPEC

Part Number: KPGA-1602SURC-KA

Hyper Red

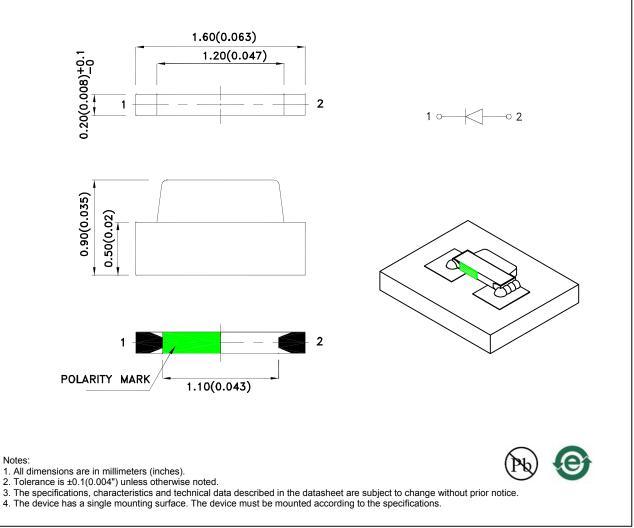
Features

- 1.6mmx0.9mm right angle SMT LED,0.2mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Moisture sensitivity level : level 3.
- Package :2000pcs / reel.
- Tinned pads for improved solderability.
- RoHS compliant.

Package Dimensions

Description

The Hyper Red source color devices are made with Al-GalnP on GaAs substrate Light Emitting Diode.



SPEC NO: DSAN1983 APPROVED: WYNEC REV NO: V.1A CHECKED: Allen Liu DATE: SEP/10/2013 DRAWN: Y.Liu PAGE: 1 OF 5 ERP: 1203013856

	Selection Guide									
	Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]				
				Min.	Тур.	201/2				
	KPGA-1602SURC-KA	Hyper Red (AlGaInP)	Water Clear	80	210	145°(H) 130°(V)				
				*20	*70					

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.
* Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	639		nm	IF=20mA
λD [1]	Dominant Wavelength	Hyper Red	631		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	20		nm	IF=20mA
VF [2]	Forward Voltage	Hyper Red	2.05	2.4	V	IF=20mA
lr	Reverse Current	Hyper Red		10	uA	Vr=5V

Notes:

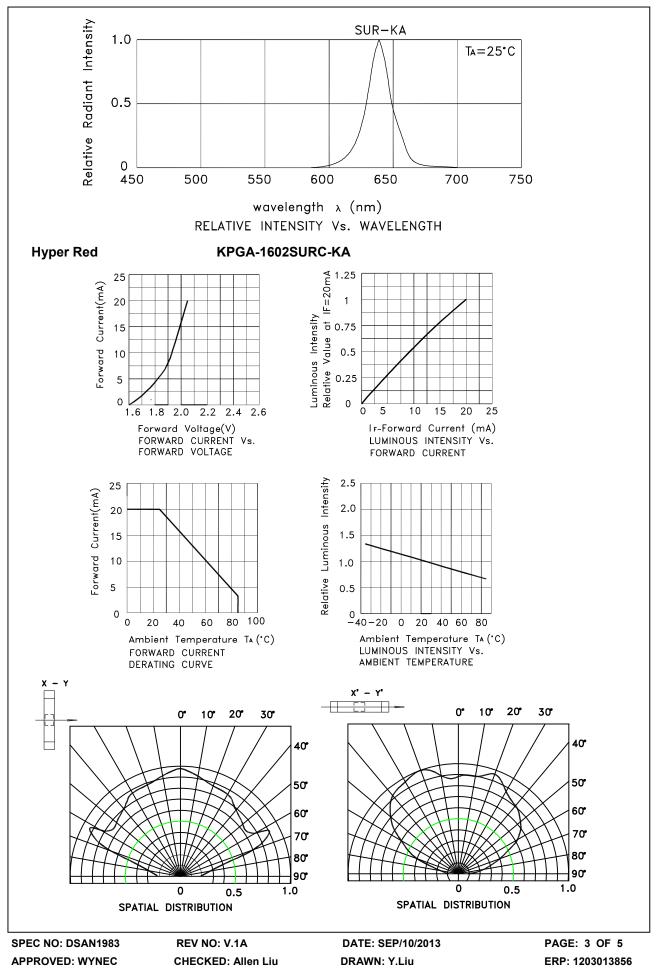
Wavelength: +/-1nm.
Forward Voltage: +/-0.1V.
Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Units		
Power dissipation	48	mW		
DC Forward Current	20	mA		
Peak Forward Current [1]	100	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +100°C			

Note:

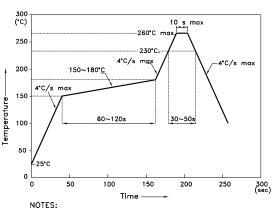
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



KPGA-1602SURC-KA

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

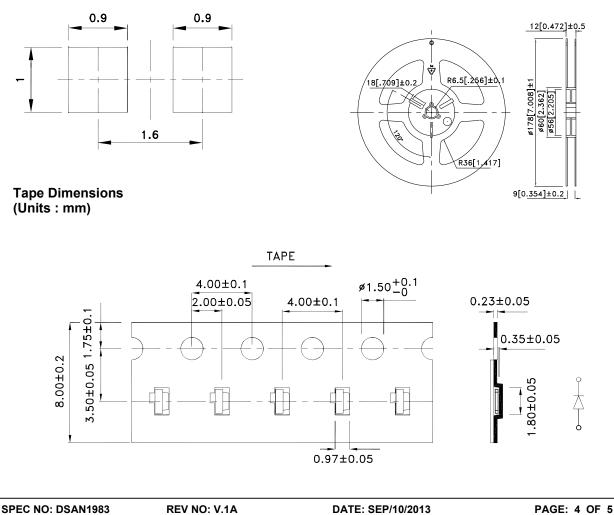
Reflow Soldering Profile For Lead-free SMT Process.



1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.

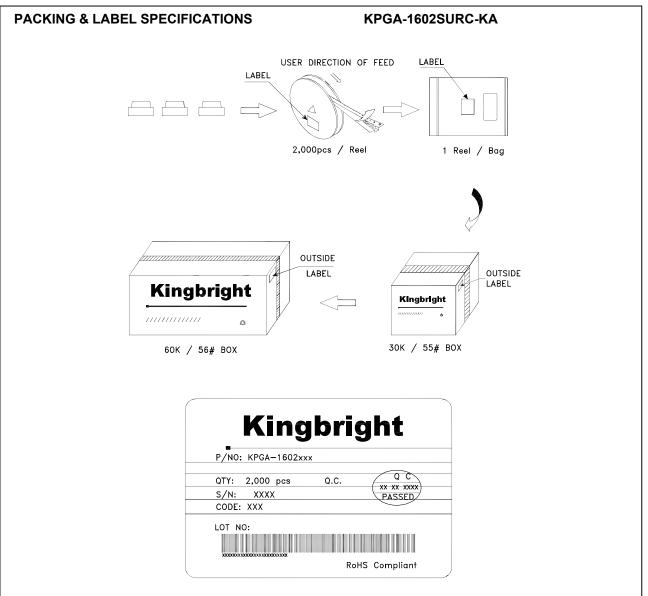


Reel Dimension



CHECKED: Allen Liu

DRAWN: Y.Liu



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